

## Special Issue

# Microstructural and Mechanical Characteristics of Welded Joints

### Message from the Guest Editors

This Special Issue aims to explore the latest research and developments in the field of electronic packaging, with a particular focus on solder joints, reliability, and interfacial metallurgy. It emphasizes friction stir welding/processing, dissimilar metal joining, and additive manufacturing. It seeks to provide a comprehensive platform for researchers and engineers to share their findings and insights on these aspects. This Special Issue covers both theory and practice, aiming to deepen understanding, promote innovation, and drive interdisciplinary breakthroughs that connect basic research with industrial application.

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### Guest Editors

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### Deadline for manuscript submissions

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## Materials

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### Message from the Editor-in-Chief

*Materials* (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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